

ECE321 – Electronics I

Lecture 8: MOSFET Threshold Voltage and Parasitic Capacitances

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Review of Last Lecture

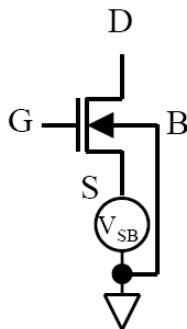
- Device Model for Linear Region
- Device Model for Saturation Region
- Channel Length Modulation

Today's Lecture

- Threshold Voltage Equation
- "Dynamic Parameters of Long Channel MOSFET"
- MOSFET Parasitic Capacitances
 - Overlap capacitances
 - Channel capacitances
 - Junction capacitances

Threshold Voltage Equation

- MOSFET is a four terminal device; Gate, Source, Drain, and Bulk.
- The Bulk may not be always connected to the Source.



Threshold Voltage Equation

- ❑ We normally assume that the bulk of the MOSFET is connected to source. However, sometimes the bulk and source are in different potentials ($V_{SB} \neq 0$). V_{SB} is called “body bias”.
- ❑ The applied V_{SB} changes the threshold voltage as shown below:

$$V_T = V_{T0} + \gamma \left(\sqrt{|2\phi_F + V_{SB}|} - \sqrt{|2\phi_F|} \right)$$

- ❑ In this equation, V_{T0} is the zero bias threshold voltage, γ is the body bias coefficient, and ϕ_F is:

$$\phi_F = \frac{KT}{q} \ln \left(\frac{N_A}{n_i} \right)$$

- ❑ Where N_A is the doping concentration in the substrate.

Example: Threshold Voltage & Body Bias

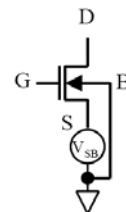
- ❑ Assume that $V_{T0}=0.8\text{V}$, $\gamma=0.6 \text{ V}^{1/2}$, $\phi_F= 0.4 \text{ V}$. Find V_T if $V_{SB}= 2.5 \text{ V}$

$$V_T = V_{T0} + \gamma \left(\sqrt{|2\phi_F + V_{SB}|} - \sqrt{|2\phi_F|} \right)$$

$$V_T = 0.8 + 0.6 \times \left(\sqrt{|2 \times 0.4 + 2.5|} - \sqrt{|2 \times 0.4|} \right) = 0.8 + 0.55 = 1.35$$

Observations:

- 1) Body bias is normally reverse bias. (why?)
- 2) More reverse body bias increases the threshold voltage.



MOSFET Threshold Voltage

- The gate potential at which the channel inverts is called the threshold voltage (V_T)
- V_T is always referenced in relation to the gate to source potential V_{GS} (this is because the surface potential needs to exceed the source to “lure” electrons away into the channel)
- V_T is comprised of four main components:
 - Work function difference between the gate and substrate
 $\phi_F(\text{substrate}) - \phi_F(\text{gate})$
 - V_{GS} component required to change the surface potential of $2\phi_F$
 - V_{GS} needed to offset the depletion region charge
 - V_{GS} needed to offset charges trapped in the gate oxide

More Detail on MOSFET Threshold Voltage

Zero body bias threshold voltage:
$$V_{T0} = \phi_{ms} + 2\phi_F + \frac{\sqrt{2qN_A\epsilon_{si}}|2\phi_F|}{C_{ox}} - \frac{Q_{ox}}{C_{ox}}$$

Where:
$$\phi_F = \frac{KT}{q} \ln\left(\frac{N_A}{n_i}\right) \quad \text{and} \quad C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$$

Threshold voltage with body bias:
$$V_T = V_{T0} + \gamma\left(\sqrt{|2\phi_F + V_{SB}|} - \sqrt{|2\phi_F|}\right)$$

Where:
$$\gamma = \frac{\sqrt{2qN_A\epsilon_{si}}}{C_{ox}}$$

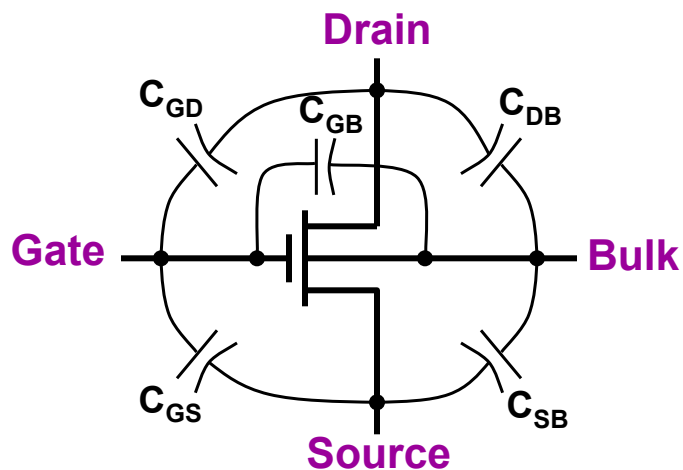
Important Facts:

- Body bias increases threshold voltage
- Threshold voltage is **positive** for normal **NMOS**
- Threshold voltage is **negative** for normal **PMOS**

MOS Capacitance

- ❑ Delay of digital CMOS circuits depends of capacitance of MOS device
- ❑ There is a trade off between parasitic capacitance and drive strength of MOS device
 - Larger C_{ox} increases the drive strength (I_{DS} equation)
 - However, larger C_{ox} increases the device parasitic capacitance
- ❑ MOS parasitic capacitance includes
 - Overlap capacitances
 - Channel capacitances
 - Junction capacitances
- ❑ Between almost every two terminals of MOS device, there is a source of parasitic capacitance

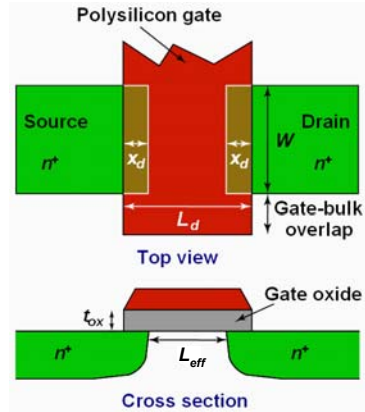
MOS Parasitic Capacitances



Overlap Capacitances

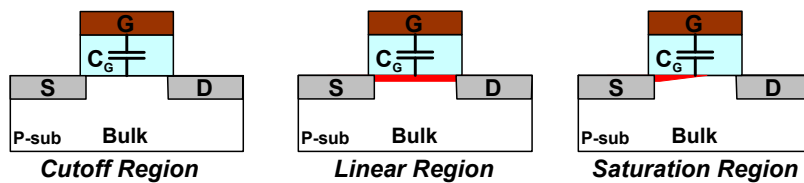
- Because of the lateral S/D diffusion, there is an overlap between gate and S/D junctions
- This overlap capacitance is a constant linear capacitance

$$C_{GSOV} = C_{GDOV} = WC_{ox}X_d$$



Channel Capacitances

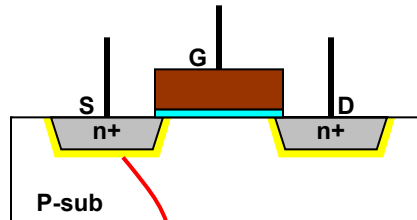
- Channel capacitance is a voltage dependent and non-linear capacitance



Operation Region	C_{GBCH}	C_{GSCH}	C_{GDCH}
Cutoff	$C_{OX}WL_{eff}$	0	0
Linear	0	$\frac{1}{2}C_{OX}WL_{eff}$	$\frac{1}{2}C_{OX}WL_{eff}$
Saturation	0	$\frac{2}{3}C_{OX}WL_{eff}$	0

Junction Capacitances

- ❑ Junction capacitance is the **depletion region** capacitance of S/D
- ❑ It is a **voltage dependent** capacitance (remember reverse biased diode)

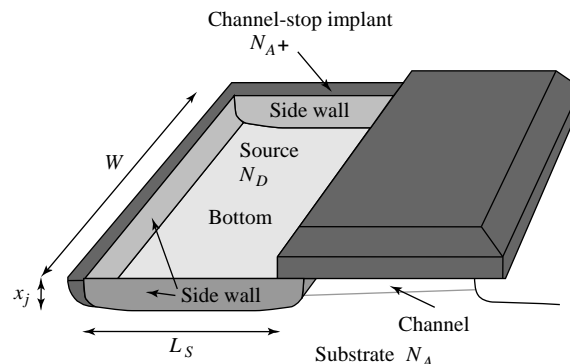


$$C_j = \frac{C_{j0}}{(1 - V_{SB}/\phi_0)^m}$$

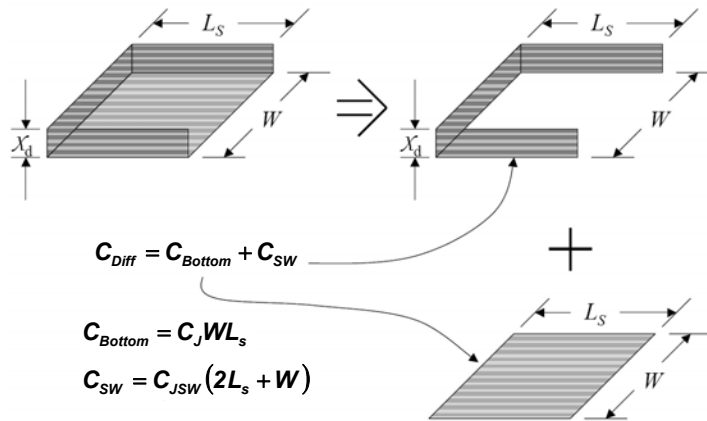
$$C_{j0} = A_D \sqrt{\left(\frac{\epsilon_{si} q}{2} \frac{N_A N_D}{N_A + N_D} \right) \phi_0^{-1}} \quad \phi_0 = \frac{KT}{q} \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

Junction Capacitance Components

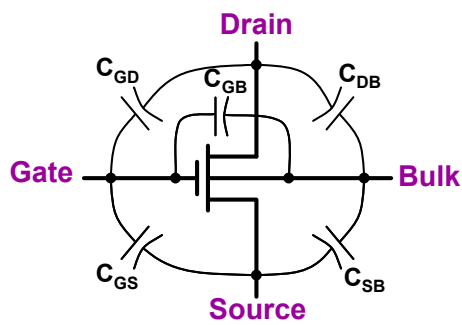
- ❑ The Junction capacitance of bottom plate is treated separately from the three non-gate edges
- ❑ The gate edge is often ignored since it is part of the conducting channel
- ❑ The bottom plate is usually step graded with $m=0.5$
- ❑ The sidewall are step graded with $m=0.33$ and face the **channel-stop implant** which has much higher doping than substrate



Junction Capacitance Components



MOS Parasitic Capacitances



$$C_{GS} = C_{GSCH} + C_{GSOV}$$

$$C_{GD} = C_{GDCH} + C_{GDOV}$$

$$C_{GB} = C_{GBCH}$$

$$C_{SB} = C_{Sdiff}$$

$$C_{DB} = C_{Ddiff}$$